

ABSTRACT

A semiconductor package is disclosed with a recess (51) for an integrated circuit die (52). The recess is made by bending or deforming all layers of a package substrate, and therefore the recess contains circuitry to connect to the integrated circuit die. The integrated circuit die is electrically connected to the package substrate by either wirebonds (53a), TAB or die solder balls (53b). The package substrate (50), a single sided printed wiring board, has a thick metal core (100) and one or more thin build up layers.

